

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S64	6	("5027191" "6483187" "6525942").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S65	4	("6020629" "6528882").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S66	10	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN. OR ("6528882").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S67	31	("5285352" "5583377" "5642261" "5741729" "5825628" "5942795" "5959356" "6008536" "6023098" "6034427" "6038137" "6117705" "6125042").PN. OR ("6282094").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S68	9	("5027191" "5710459" "5741729" "6212076" "6282094" "6483187" "6525942" "6657864" "6882537").PN. OR ("6954360").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S69	6	S68 not S64	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S70	9	("5027191" "5710459" "5741729" "6212076" "6282094" "6483187" "6525942" "6657864" "6882537").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S71	0	(3061/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S72	2899	(361/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S73	120	S72 and die with pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

## EAST Search History

S74	540	(257/670).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S75	18101	<i>pad with finger</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S76	50	S74 and <i>pad with finger</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S77	9733	(257/66\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S78	328	S77 and <i>pad near5 finger</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S79	304	S78 not S76	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S80	246	S78 not S76	USPAT	OR	ON	2006/11/10 15:11
S81	74	("5479050"   "5594234"   "5663597").PN. OR ("6211462"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S82	8832	(257/67\$1).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S83	365	S82 and <i>pad near5 finger</i>	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

## EAST Search History

S84	191	S83 not S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S85	18101	pad with finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S86	11870	pad near5 finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S87	8832	S82 S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S88	365	S87 and S86	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S89	0	S88 not ( S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S90	7641	pad near5 tip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S91	747	S90 and S86	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S92	716	S91 not ( S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

## EAST Search History

S93	6755	S90 not S75	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S94	176	S87 and S93	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S95	176	S94 not ( S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S96	2546	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near5 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S97	2147	S96 not S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S98	2169	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S99	1818	S98 not S87	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S100	685	(IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (extend\$3 attach\$3 prolong\$3) with (phalange thumb tip finger tip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S101	15246	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad ). ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

## EAST Search History

S10 2	272	S100 and S101	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 3	216	S102 not ( S84 S81 S79 S78 S95)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 4	139	S102 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 5	108	S104 not ( S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 6	503	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad near4 (phalange thumb tip finger tip)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 7	388	S106 not (S103 S84 S81 S79 S78)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 8	1	S104 and S107	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S10 9	86	S107 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 0	1419	((IC chip die integrated near1 circuit semiconductor siliocn) with pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 1	879	((IC chip die integrated near1 circuit semiconductor siliocn) near2 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11

## EAST Search History

S11 2	1866277	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 3	600	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 4	388	S113 not S107	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 5	78	S113 and (PCB board BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 6	12	("4362899"   "4890155"   "5194833").PN. OR ("5373187").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S11 7	199	(IC chip die integrated near1 circuit semiconductor siliocn) near2 pad same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 8	0	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S11 9	26	((IC chip die integrated near1 circuit semiconductor siliocn) near1 pad with (phalange thumb tip finger tip)) same PWB	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:11
S12 0	28	("4551746"   "4551747"   "5089881"   "5218230"   "5513076").PN. OR ("5691568").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 1	76	("5519576"   "5672909"   "5691568").PN. OR ("5903050").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11

## EAST Search History

S12 2	297	("20010008305" "20010014538" "20020011654" "20020027297" "20020140061" "20020140068" "20020163015" "20030030131" "20030073265" "2596993" "3435815" "3734660" "3838984" "4054238" "4189342" "4258381" "4289922" "4301464" "4332537" "4417266" "4451224" "4530152" "4541003" "4646710" "4707724" "4727633" "4737839" "4756080" "4812896" "4862245" "4862246" "4907067" "4916519" "4920074" "4935803" "4942454" "4987475" "5018003" "5029386" "5041902" "5057900" "5059379" "5065223" "5070039" "5087961" "5091341" "5096852" "5118298" "5151039" "5157475" "5157480" "5168368" "5172213" "5172214" "5175060" "5200362" "5200809" "5214845" "5216278" "5218231" "5221642" "5250841" "5252853" "5258094" "5266834" "5273938" "5277972" "5278446" "5279029" "5281849" "5294897" "5327008" "5332864" "5335771" "5336931" "5343076" "5358905" "5365106" "5381042" "5391439" "5406124" "5410180" "5414299" "5424576" "5428248" "5435057" "5444301" "5452511" "5454905" "5474958" "5484274" "5493151" "5508556" "5517056" "5521429" "5528076" "5534467" "5539251" "5543657" "5544412" "5545923" "5581122" "5592019" "5592025" "5594274" "5595934" "5604376" "5608265" "5608267" "5625222" "5633528" "5639990" "5640047" "5641997" "5643433" "5644169" "5646831" "5650663" "5661088" "5663593" "5665996" "5673479").PN. OR ("5683806" "5689135" "5696666" "5701034" "5703407" "5710064" "5723899" "5724233" "5726493" "5736432" "5745984" "5753532" "5753977" "5766972" "5770888" "5776798" "5783861" "5801440" "5814877" "5814881" "5814883" "5814884" "5817540" "5818105" "5821457" "5821615" "5834830" "5835988" "5844306" "5856911" "5859471" "5866939" "5871782" "5874784" "5877043" "5886397" "5886398" "5894108" "5897339" "5900676" "5903049" "5903050" "5909053" "5915998" "5917242" "5939779" "5942794" "5951305" "5959356" "5969426" "5973388" "5976912")	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
11/10/06 4:28:51 PM		"5977613" "5977615" "5977630" "6001671" "6013947" "6018189"				Page 7

## EAST Search History

S12 3	1	"5594234".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 4	30	("4714952"   "5252783"   "5428248"   "5436500"   "5440170").PN. OR ("5594234").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/11/10 15:11
S12 5	2487	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S12 6	1447	(257/691).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:11
S12 7	1476	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:34

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1476	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/11/10 15:37
L2	120	1 and finger with die near2 pad	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/10 15:51
L3	492	((pad electrode contact land) and (encomps\$5 encircl\$4 enclos\$4 surround\$4) and ( (IC chip die integrated near1 circuit wafer die semiconductor silicon) near1 pad)).clm.	US-PGPUB	OR	ON	2006/11/10 15:56
L4	16	((pad electrode contact land) and (finger falange) and (encomps\$5 encircl\$4 enclos\$4 surround\$4) and ( (IC chip die integrated near1 circuit wafer die semiconductor silicon) near1 pad)).clm.	US-PGPUB	OR	ON	2006/11/10 15:57
L5	291	((pad electrode contact land) and (finger falange layer film) and (encomps\$5 encircl\$4 enclos\$4 surround\$4) and ( (IC chip die integrated near1 circuit wafer die semiconductor silicon) near1 pad)).clm.	US-PGPUB	OR	ON	2006/11/10 15:57